FTDI Unveils Development and Programming Modules for its HID-Class USB Controller IC

In order to continue providing engineers with comprehensive support when implementing USB into their embedded systems, FTDI Chip has just introduced 2 new board level products, as well as a new IC.

The UMFTPD3A programmer module is designed specifically for use with the company's development hardware and ICs containing either internal one-time programmable (OTP) memory or eFUSE logic (which are both used to store USB vendor ID, product ID product description data, etc.), namely the FT260 and FT4222H offerings. It offers assistance to engineers as they carry out programming of the OTP/eFUSE directly through FTDI Chip's proprietary FT_Prog programming package and provides an external programming voltage (V_{PP}) that covers 1.5 to 6.5V. The on-board micro USB-B type connector facilitates connection of this module to the host system via a standard USB A to micro B cable.

The UMFT260EV1A is a compact, easy to utilise development module that relates to the company's recently announced FT260Q, HID-class USB bridging IC (which has I^2C and UART bus conversion capabilities). This module will present engineers with a valuable resource for adding connectivity to human machine interfaces and other computing peripherals. It fits a standard 20.32mm (0.8-inch) wide 24-pin DIP socket, with pins on a 2.54mm (0.1-inch) pitch. Like the UMFTPD3A, this product has a micro USB-B connector thereby allowing a

standard USB A to micro B cable connection to the host systems. In addition to the UMFT260EV1A module, to further expand the scope of the FT260 series, FTDI Chip has also introduced a 28-pin TSSOP packaged version of the IC that will make it more convenient for pick-and-place procedures. The new FT260S is USB 2.0 Full Speed compliant (supporting 12Mbps data rates). It has 4 different I^2C bus speed modes, plus USB battery charger detection. As both the FT260S and FT260Q rely on standard class drivers the installation of vendor-specific drivers can be avoided.

For information on the UMFTPD3A visit:

http://www.ftdichip.com/Products/Modules/DevelopmentModules.htm#UMFTPD3A

For information on the UMFT260EV1A visit:

http://www.ftdichip.com/Products/Modules/DevelopmentModules.htm#UMFT260EV1A

For information on the FT260 visit: www.ftdichip.com/ft260

About FTDI Chip
FTDI Chip develops innovative silicon solutions that enhance interaction with the latest in global technology. The major objective from the company is to 'bridge technologies' in order to support engineeers with highly sophisticated, feature-rich, robust and simple-to-use product platforms. These platforms enable creation of electronic designs with high performance, low peripheral component requirements, low power budgets and minimal board real estate.

FTDI Chip's long-established, continuously expanding Universal Serial Bus (USB) product line boasts such universally recognized product brands as the ubiquitous R-Chip, X-Chip, Hi-Speed and SuperSpeed USB 3.0 series. In addition to both host and bridge chips, it includes highly-integrated system solutions with built-in microcontroller functionality. The company's Embedded Video Engine (EVE) graphic controllers each pack display, audio and touch functionality onto a single chip. The unique, streamlined approach utilised by these ICs allow dramatic reductions in the development time and bill-of-materials costs involved in next generation Human Machine Interface (HMI) implementation. FTDI Chip also provides families of highly-differentiated, speed-optimised microcontroller units (MCUs) with augmented connectivity features, specifically designed with compatibility to its USB and Display product lines in mind. These MCUs are targeted for key applications where they can add value with their superior processing performance and high levels of operational efficiency.

FTDI Chip is a fab-less semiconductor company, partnered with the world's leading foundries. The headquarter is located in Glasgow, UK and is supported with research and development facilities in Glasgow, Singapore and Taipei (Taiwan) plus regional sales and techical support sites in Glasgow, Taipei, Tigard (Oregon, USA) and Shanghai (China).

For more information go to http://www.ftdichip.com

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